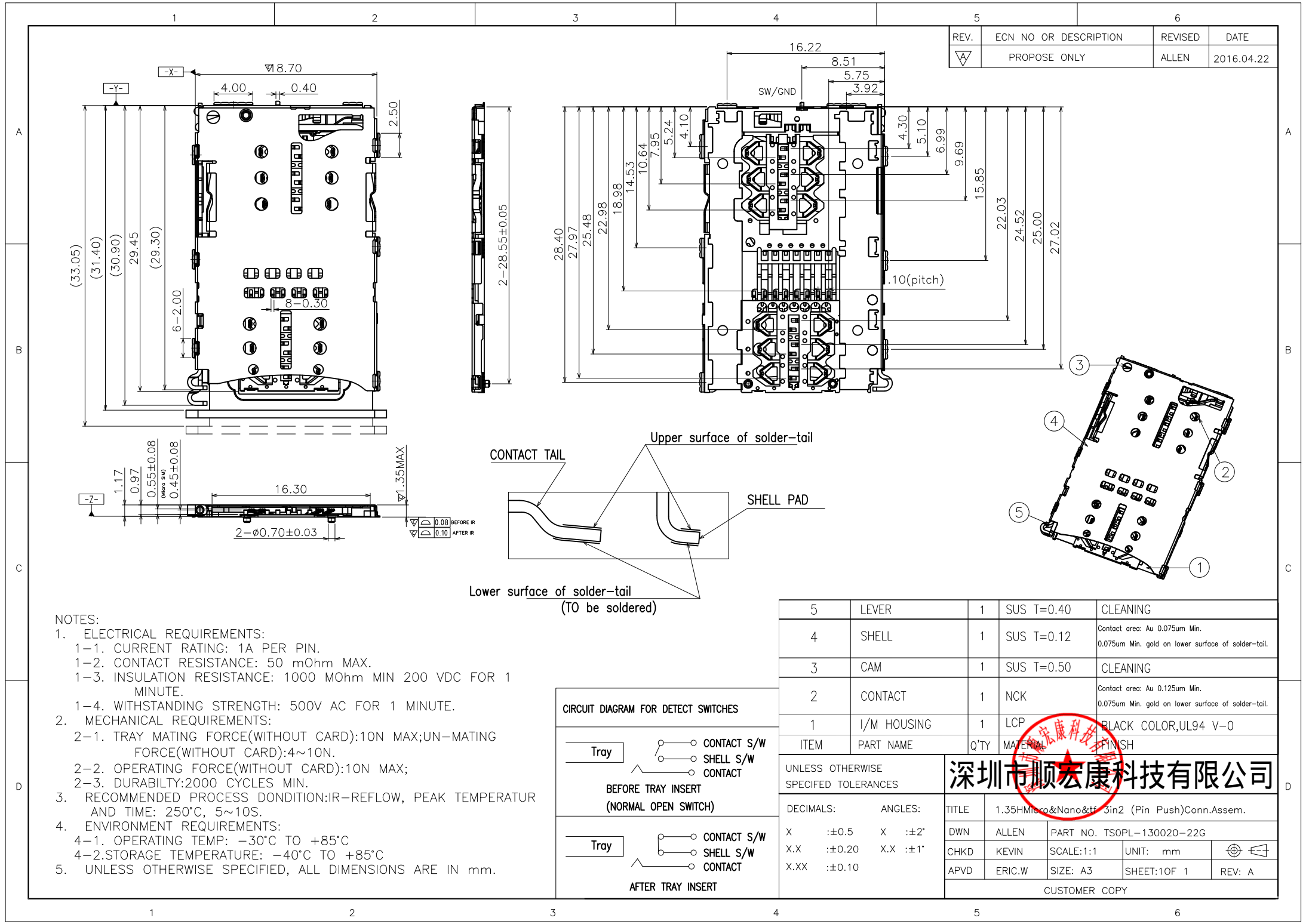
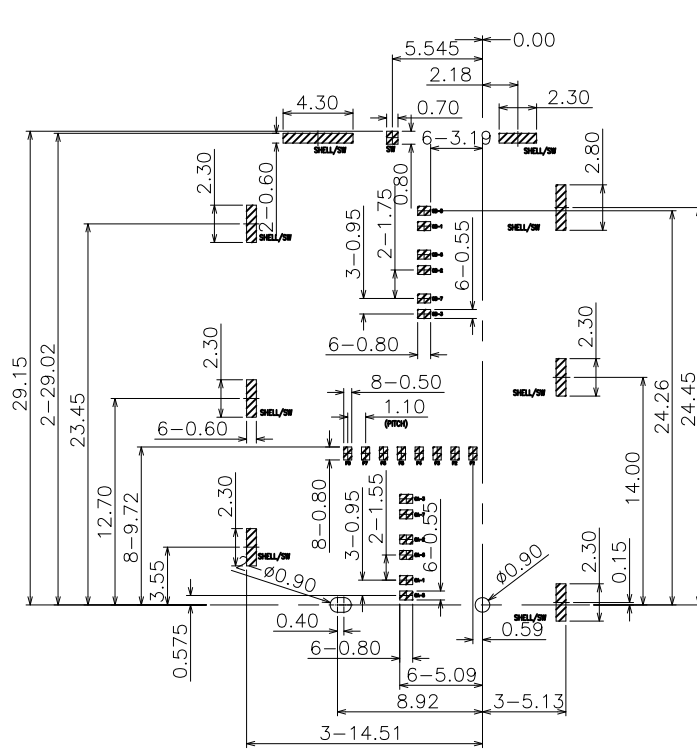
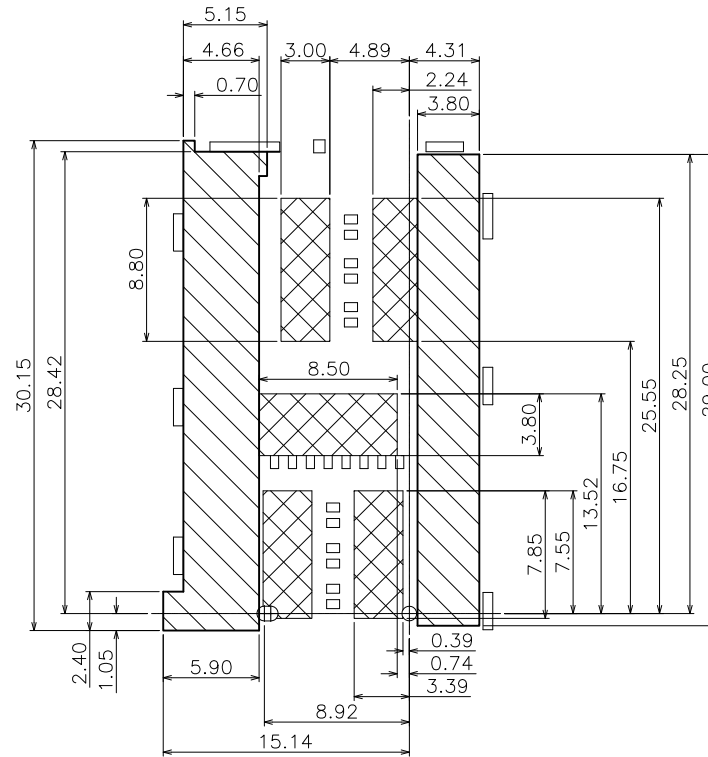




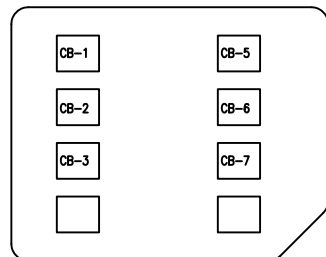
REV.	ECN NO OR DESCRIPTION	REVISED	DATE
	PROPOSE ONLY	ALLEN	2016.04.22



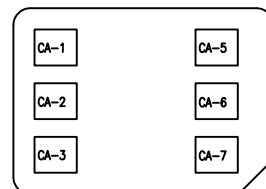
RECOMMENDED P.W. BOARD PATTERN LAYOUT
(TOLERANCE: ± 0.05)
STENCIL THICKNESS: 0.10MM



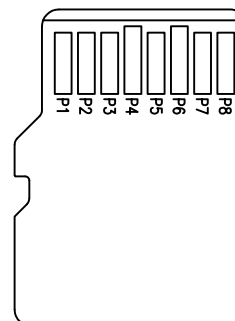
- PATTERNS
- GROUND NO PATTERNS
- NO SURFACE LAYER COPPER



MICRO SIM CARD ELECTRICAL



NAND SIM CARD ELECTRICAL



SD CARD ELECTRICAL

ITEM	FUNCTION	Remark
CA-1	VCC OF SIM	SIM1
CA-2	RST OF SIM	
CA-3	CLK OF SIM	
CA-4	VCC OF SIM	
CA-5	GND OF SIM	
CA-6	VPP OF SIM	
CA-7	DATA OF SIM	
CB-1	VCC OF SIM	SIM2
CB-2	RST OF SIM	
CB-3	CLK OF SIM	
CB-4	VCC OF SIM	
CB-5	GND OF SIM	
CB-6	VPP OF SIM	
CB-7	DATA OF SIM	
P-1	DAT2 OF MSD	SD
P-2	CD/DAT3 OF MSD	
P-3	CMD OF MSD	
P-4	VDD OF MSD	
P-5	CLK OF MSD	
P-6	VSS OF MSD	
P-7	DAT0 OF MSD	
P-8	DAT1 OF MSD	
SW	TARY DETECTION SW(SW Contact)	S/W Solder
SHELL/SW	TARY DETECTION SW(In Shell)	

UNLESS OTHERWISE SPECIFIED TOLERANCES		深圳市顺宏康科技有限公司				
DECIMALS:		ANGLES:		TITLE		
				1.35HMicro&Nano&tf 3in2 (Pin Push)Conn.Assem.		
X	:±0.5	X	:±2°	DWN	ALLEN	PART NO. TS0PL-130020-22G
X.X	:±0.20	X.X	:±1°	CHKD	KEVIN	SCALE: 1:1
X.XX	:±0.10			UNIT: mm		
		APVD	ERIC.W	SIZE: A3	SHEET: 1 OF 1	REV: A
CUSTOMER COPY						